CLAIMS

1. A tray for use in storing a wafer with a tape frame in a storage container, the wafer with the tape frame comprises a ring-shaped frame, a dicing tape and a semiconductor wafer, the dicing tape is stuck on a rear surface of the ring-shaped frame, the semiconductor wafer is supported on the dicing tape, wherein,

the tray has a substantially circular shape and is positioned on a upper side and a lower side of the wafer with the tape frame;

a front surface of the tray has a substantially flat portion for mounting the wafer with the tape frame, at least a portion of a outer peripheral portion of the front surface of the tray includes a convex portion; and

a projecting portion is formed on a rear surface of the tray so that the projection portion is positioned outside an outer periphery of the semiconductor wafer of the wafer with the tape frame and right above the exposed portion of the dicing tape when the tray is positioned on the wafer with the tape frame.

2. A tray according to Claim 1, wherein the rear surface of the tray is inclined from a point between the projecting portion and the outer peripheral portion of the semiconductor wafer as a starting point and toward a center portion, a tilt angle θ of the rear surface is set in a range between 0.1° and 1.0°.